SOT-23



beyond boundaries...

ASYMMETRICAL TVS DIODE FOR EXTENDED COMMON-MODE RS-485

DESCRIPTION:



ALPN07122BT23 Surface mount Asymmetrical TVS Diode for Extended Common-Mode RS-485 features 392 Watts (tp = 8/20µs) of power handling capability to accommodate the higher transient voltage levels which may be expected in extended common mode applications. ALPN07122BT23 may be used to protect devices from transient voltages resulting from electrostatic discharge (ESD), electrical fast transients (EFT), and lightning.

ALPN07122BT23 replaces four discrete components by integrating two 12V and two 7V TVS diodes in a single package. The integrated design aids in reducing voltage over-shoot associated with trace inductance. The low clamping voltage of the ALPN07122BT23 minimizes the stress on the protected transceiver. The SOT23 package allows flexibility in the design of "crowded" circuit boards.

FEATURES

- 392 watts peak pulse power ($t_p = 8/20\mu s$)
- Transient protection for asymmetrical data lines to IEC 61000-4-2 (ESD) ±30kV (air), ±30kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns) IEC 61000-4-5 (Lightning) 14A (8/20μs)
- Protects two +12V to -7V lines
- Low capacitance
- Low clamping voltage
- Low leakage current
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen-free part, ex. ALPN07122BT23-H

APPLICATIONS

- Protection of RS-485 transceivers with extended common-mode range
- Security systems
- **Automatic Teller Machines**
- **HFC** systems
- Networks

MECHANICAL DATA

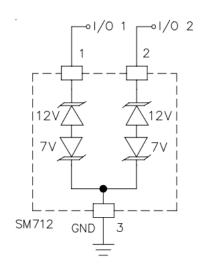
- Molding compound flammability rating: UL 94V-0.
- Case: Molded plastic, SOT-23.
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026.
- Mounting Position: Any.
- Weight: Approximately 0.008 gram.

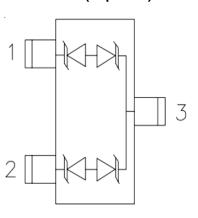


CIRCUIT DIAGRAM

PIN DESCRIPTION

SOT23 (Top View)







beyond boundaries...

ELECTRICAL CHARACTERISTICS

ELECTRICAL CHARACTERISTICS (at T _A = 25 °C unless otherwise noted)									
PARAMETER	SYMBOL	CONDITIONS	Pins 1 to 3 and 2 to 3 (12V TVS)		Pins 1 to 3 and 2 to 3 (7V TVS)			UNIT	
			MIN	ТҮР	MAX	MIN	TYP	MAX	
Reverse Stand-Off Voltage	V _{RWM}	Pin 3 to 1 or Pin 2 to 1			12			7	V
Reverse Breakdown Voltage	V_{BR}	I _{PT} = 1mA	13.3			7.5			V
Reverse Leakage Current	I _R	$V_R = V_{RWM}$			0.5			0.5	μΑ
Clamping Voltage 1	V _{C1}	I _{PP} = 5A, t _p = 8/20μs			22			16	V
Clamping Voltage 2	V _{C2}	I _{PP} =17A, t _p = 8/20μs			28			20	V
Junction Capacitance 1	C _{J1}	V _R = 0V, f = 1MHz		45	75		45	75	pF
Junction Capacitance 2	C _{J2}	V _R = V _{RWM} , f = 1MHz		25			30		pF

ABSOLUTE MAXIMUM RATINGS

ABSOLUTE MAXIMUM RATINGS (at T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	VALUE	UNIT		
IEC 61000-4-2 (ESD) Air Contact	V _{ESD}	±30 ±30	kV		
Peak pulse current (t _p =8/20us waveform)	Ірр	14	А		
Peak pulse power (t _p =8/20us waveform)	P _{PP}	392	w		
Lead Soldering Temperature	Τι	260 (10 sec.)	°C		
Operating Junction Temperature Range	Tı	-55 to +150	°C		
Storage Temperature Range	T _{STG}	-55 to +150	°C		



TYPICAL DEVICE CHARACTERISTICS CURVES

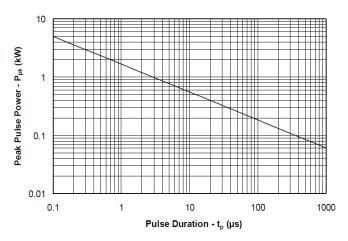


Fig1. Peak Pulse Power vs. Pulse Time

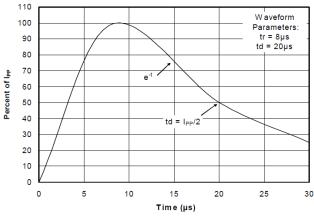


Fig3. Pulse Waveform

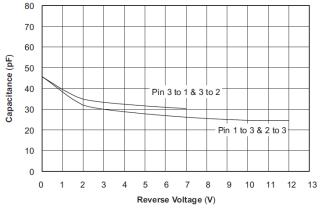


Fig5. Capacitance vs. Reverse Voltage

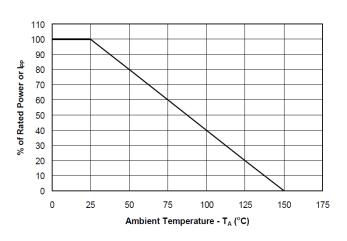


Fig2. Power Derating Curve

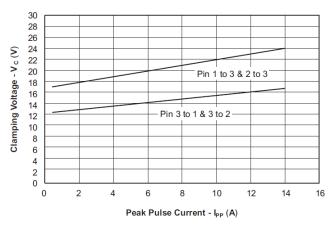


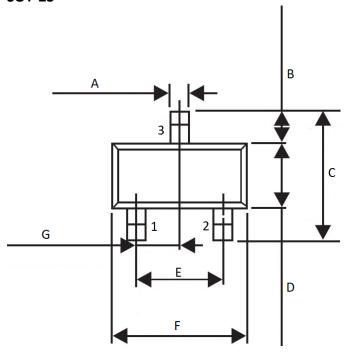
Fig4. Clamping Voltage vs. Peak Pulse Current



beyond boundaries...

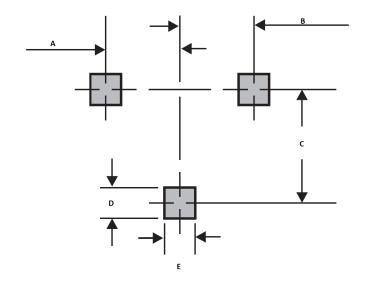
PACKAGE INFORMATION

SOT-23



OUTLINE DIMENSIONS						
	MILLIN	METERS	INCHES			
SYMBOL	MIN	MAX	MIN	MAX		
А	0.30	0.50	0.012	0.020		
В	0.55	(Ref)	0.022 (Ref)			
С	2.25	2.55	0.089	0.100		
D	1.20	1.40	0.047	0.055		
E	1.80	2.00	0.071	0.079		
F	2.80	3.00	0.110	0.118		
G	0.95	(Ref)	0.037	(Ref)		

PAD LAYOUT



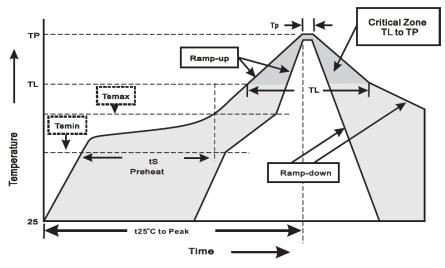
OUTLINE DIMENSIONS					
SYMBOL	MILLIMETERS	INCHES			
Α	0.95	0.037			
В	0.95	0.037			
С	2.00	0.079			
D	0.90	0.035			
E	0.80	0.031			

beyond boundaries...

SOLDERING PARAMETERS

SUGGESTED THERMAL PROFILES FOR SOLDERING PROCESSES

- 1. Storage environment: Temperature=5 °C~40 °C Humidity=55% ±25%
- 2. Reflow soldering of surface-mount devices



3. Reflow soldering

PROFILE FEATURE	SOLDERING CONDITION
Average ramp-up rate (TL to TP)	<3 °C/sec
Preheat	
- Temperature Min (Tsmin)	150 °C
- Temperature Max (Tsmax)	200 °C
- Time (min to max) (ts)	60 ~ 120 sec
Tsmax to TL	
- Ramp-upRate	<3 °C/sec
Time maintained above:	
- Temperature (TL)	217 °C
- Time(tL)	60 ~ 260 sec
Peak Temperature (TP)	255 °C-0/+5 °C
Time within 5 °C of actual Peak	10 ~ 30 sec
Temperature(tP)	
Ramp-down Rate	<6 °C/sec
Time 25 °C to Peak Temperature	<6 minutes



ALPN07122BT23

SOT-23

PRODUCT HIGH RELIABLITY TEST CAPABILITIES

ITEM	TEST CONDITIONS	STANDARD
Solder Resistance	At 260±5°C for 10±Sec.	MIL-STD-750D
		METHOD-2031
Solderability	At 245±5°C for 5 sec.	MIL-STD-202F
		METHOD-208
High Temperature Reverse Bias	V_{BR} = V_{BR} Min * 80% at T_J =150°C for 168 hrs.	MIL-STD-750D
		METHOD-1038
Pressure Cooker	15P _{SIG} at T _A =121°C for 4Hrs	JESD22-A102
Temperature Cycling	-55°C to +125°C dwelled for 30min and	MIL-STD-750D
	transferred for 5min. total 10 cycles.	METHOD-1051
Humidity	At T _A =85°C, RH=85% for 1000hrs.	MIL-STD-750D
		METHOD-1021
High Temperature Storage Life	At 150°C for 1000hrs.	MIL-STD-750D
		METHOD-1031



CUSTOMER NOTE:

DISCLAIMER

The product information and the selection guide facilitates the selection of the ALPINESEMI™'s Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review the Data sheet(s) so as to confirm that the Device(s) meets functionality parameters for your application. The information furnished on the Data Sheet and the ALPINESEMI™'s Web Site is believed to be accurate and reliable at the time of preparation of this document. ALPINESEMI™ however, does not assume any inaccuracies that may arise when the components are mounted and removed. Furthermore, ALPINESEMI™ does not assume liability whatsoever, arising out of the application or the use of any of ALPINESEMI™'s product(s). Neither, does it convey any license under its patent rights nor the rights of others. These products are not guaranteed for use in life saving/support appliances or systems. ALPINESEMI™'s customers using these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and ALPINESEMI™ will not be responsible in any way(s) for any damage(s) resulting from such use.

Please check the website www.alpinesemi.com for continues updates and revision of datasheets.

DESIGN CHANGES: ALPINESEMI™ strives for continuous improvement and reserves the right to change the specifications of its products without prior notice. ALPINESEMI™ reserves the right to discontinue product lines without prior notice. Any product selection is a recommendation based on best understanding of such product(s) by our engineers. However, buyers are advised to rely on their own judgment for such selection of the products.

ALPINESEMI™ makes no warranty, representation or guarantee regarding the suitability of its products for any particular applications. Neither does ALPINESEMI™ assume any liability arising out of the applications nor the use of such products. ALPINESEMI™ specifically disclaims all liabilities either consequential or incidental.

All rights of the product and datasheet are reserved to ALPINESEMI™.

All logos and information provided in the datasheets are for reference only. Any registered and/or trademark/logos belonging to respective companies be the property of those companies. ALPINESEMI™ extends the courtesy to them, if any of the information found in its datasheet.

Component Disposal Instructions

- 1. ALPINESEMI™ Semiconductor Devices are RoHS compliant and hence customers are requested to dispose as per the prevailing Environmental Legislation put forth in their specific country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).



sales@alpinesemi.com www.alpinesemi.com